

Double-coated adhesive tape

TR-5325F

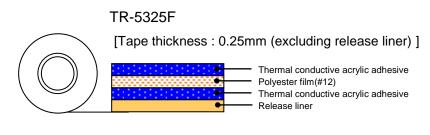
Outline

Nitto Denko thermal conductive adhesive tape TR-5325F offers superior thermal conductive property by using the thermal conductive adhesive layer.

TR-5325F acquires flammability UL94 V-0 certification.

TR-5325F offers excellent workability and processability by adopting the polyester film as base material. The tape can be used various area such as electronics.

Structure





Features

- Superior thermal conductive property.
- Excellent adhesion and superior adhesive reliability.
- Flammability UL94 V-0 [Halogen-free]. [file No. : QMFZ2.E52859]
- Excellent workability and processability.
- Ten restricted substances by RoHS are not contained.

Applications

- Fixing of LED substrate to chassis
- Fixing of CPU to heat sink or heat radiation fan
- Fixing of various semiconductor packages to heat sinks
- Fixing of electronic components to heat radiation sheet

Standard Sizes

Tape thickness (mm)	Width (mm)	Length (m)
0.25	10 - 1000	20

For details, please contact us.

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■180 degree peeling adhesion for each substrate

Substrate	TR-5325F
Stainless steel plate	11.4
Aluminum plate (A1050)	9.8
Aluminum plate (A6063)	12.4
Acrylic plate	13.3
Glass epoxy plate	17.2
Bakelite plate	19.2
Ceramics plate	13.7
White solder resist for LED	33.8

(Unit: N/20 mm) Tape area: 20mm width Lining material: PETfilm#25 Pressing condition:

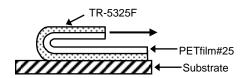
1 pass back and forth with 2-kg roller

at 23 degree C/50%RH

Applying condition: 23 degree C/50%RH x 30min

Peeling speed: 300 mm/min Peeling angle: 180 degree

Measurement temperature: 23 degree C/50%RH



■180 degree peeling adhesion -Aging(durability) at each condition after applying

Condition	TR-5325F
Initial (23 degree C/50%RH x30min)	11.4
23 degree C×42 days (1000 hrs)	13.8
60 degree C×42 days (1000 hrs)	17.4
100 degree C×42 days (1000 hrs)	21.3
120 degree C×42 days (1000 hrs)	25.0
85 degree C/85%RH×42 days (1000 hrs)	24.9
Thermal shock [1000cycles]*1	22.6

(Unit: N/20 mm)

Substrate: Stainless steel plate Lining material: PET film#25

Pressing condition:

1 pass back and forth with 2-kg roller at 23 degree C/50%RH

Applying condition: Refer to the left fig. Peeling speed: 300 mm/min

Peeling angle: 180 degree

Measurement temperature: 23 degree C/50%RH

*1: Thermal shock condition [-40 degree C x 30min->125 degree Cx30min-->] x 1000 cycles



Holding power

Temperature	TR-5325F
23 degree C	0.1
40 degree C	0.1
80 degree C	0.1
100 degree C	0.1

(Unit:mm/hr)
Substrate: Aluminum plate
Applying condition:
Measurement temperature x 30min
Measurement temperature:
23 degree C, 40 degree C,
80 degree C, 100 degree C
Tape area: 10mm x 10mm
Load: 0.98N(100g)

Aluminum plate TR-5325F

PET film#25

W) 0.98N

Load time: 1 hr

Holding power -Aging(durability) at each condition after applying

Condition	TR-5325F
Initial (23 degree C/50%RH)	0.1
23 degree C×42 days (1000 hrs)	0.1
60 degree C×42 days (1000 hrs)	0.1
100 degree C×42 days (1000 hrs)	0.1
60 degree C/90%RH×42 days (1000 hrs)	0.1
Thermal shock [1000cycles]*1	0.1

(Unit: mm/hr) Substrate: Aluminum plate

Applying condition: Refer to the left fig. Measurement temperature:40 degree C.

Tape area: 10mm x 10mm Load: 0.98N(100g) Load time: 1 hr

*1: Thermal shock condition

[-40 degree C x 30min->125 degree Cx30min-->]

x 1000 cycles



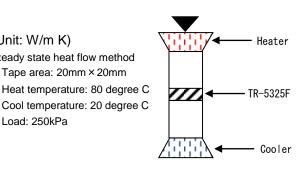
Thermal conductivity

	TR-5325F
Thermal conductivity	0.7

(Unit: W/m K)

Steady state heat flow method Tape area: 20mm × 20mm Heat temperature: 80 degree C

Load: 250kPa



Thermal resistance

	TR-5325F
Thermal resistance	3.5

(Unit: cm2·K/W)

Steady state heat flow method Tape area: 20mm × 20mm Heat temperature: 80 degree C Cool temperature: 20 degree C

Load: 250kPa

Thermal conductivity -Aging(durability) at each condition after applying

Condition	TR-5325F
Initial (23 degree C/50%RH)	0.7
60 degree C×42 days (1000 hrs)	0.7
100 degree C×42 days (1000 hrs)	0.7
120 degree C×42 days (1000 hrs)	0.7
85 degree C/85%RH×42 days	
(1000 hrs)	0.7
Thermal shock [1000cycles]*1	0.7

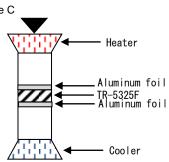
(Unit: W/m K)

Applying condition: Refer to the left fig.

Steady state heat flow method Substrate: Aluminum foil Tape area: 20mm × 20mm Heat temperature: 80 degree C Cool temperature: 20 degree C

Load: 250kPa

*1: Thermal shock condition [-40 degree C x 30min-> 125 degree Cx30min-->] x 1000 cycles



Thermal resistance -Aging(durability) at each condition after applying

Condition	TR-5325F
Initial (23 degree C/50%RH)	4.0
60 degree Cx42 days (1000 hrs)	4.0
100 degree Cx42 days (1000 hrs)	4.1
120 degree Cx42 days (1000 hrs)	4.0
85 degree C/85%RH×42 days (1000 hrs)	3.9
Thermal shock [1000cycles]*1	4.2

(Unit: cm²·K/W)

Applying condition: Refer to the left fig.

Steady state heat flow method Substrate: Aluminum foil Tape area: 20mm × 20mm Heat temperature: 80 degree C Cool temperature: 20 degree C

Load: 250kPa

*1: Thermal shock condition

[-40 degree C x 30min->125 degree Cx30min-->]

x 1000 cycles

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Flammability

	TR-5325F
UL94	V-0
	QMFZ2 E52859

(Unit : -)

Measurement condition: Refer to UL94 V test.

Electrical insulating property

	TR-5325F
Breakdown voltage	8.9

(Unit: kV)

Measurement temperature: 23 degree C Measurement humidity: 50%RH

Voltage rising rate: 1kV/s

Load: 4.9N

●Total VOC emission

Condition	TR-5325F
80 degree Cx0.5 hrs	50
130 degree Cx0.5 hrs	130

(Unit: µg/g)

Tape area: 5cm²

Applying condition: Refer to the left fig. Heating method: 20mL vial bottle

Measurement: Quantity of volatile gas 1mL



Precautions when using

- Remove all oil, moisture and dirt from the surface of the substrate before applying.
- The tape employs pressure-sensitive adhesive. Be sure to apply pressure with a roller or press when applying. Failure to do so could affect properties or appearance.
- ●The tape may not adhere well to significantly uneven or distorted surfaces. Level off the surface as much as possible before applying.
- Avoid setting or using such that significant stress is placed on the tape for several hours after application.

Precautions when storing

- Be sure to keep the tape in its box when not using.
- Keep in a cool dark place not exposed to direct sunlight.

Safety precautions

WARNING

- •Make sure the product is suitable for the application (objective and conditions) before attempting to use. The tape may come off depending on the substrate to or conditions under which it is applied.
- •Use in combination with another method of joining if there is possibility of an accident.

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